

ABSTRACT

The present invention provides an electroplating apparatus. A solid anode, a meshed anode or a perforated anode is arranged in the anode region to serve as an inert anode. And the constant distance is maintained between the inert anode and a substrate, so as to form a stable electric field on the surface of the substrate, thereby improving the uniformity of electroplating. An active anode is arranged below the inert anode in the anode region, so as to continuously replenish metal ions during the electroplating process, so that the metal ions can be more sufficiently conveyed to the substrate, thereby playing a role in improving the uniformity of electroplating. Components such as a rectifying plate, a fluid dispersion pipe or a stirring member are arranged in the anode region, so as to uniformly disperse the anode liquid, thereby further improving the uniformity of electroplating.